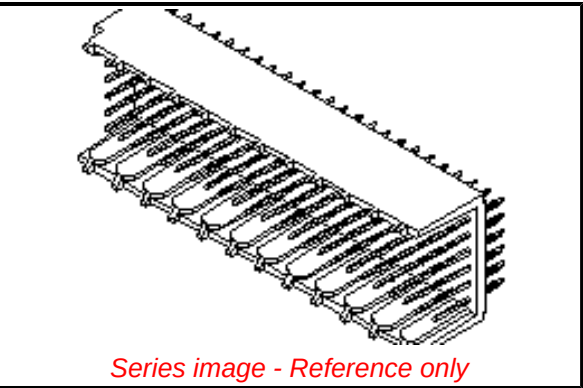


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Part Number: [0736420200](#)
Status: **Active**
Overview: [HDM Backplane Connector System](#)
Description: HDM Board-to-Board Backplane Header, Vertical, Press-Fit, Open End, 72 Circuits



Series image - Reference only

Documents:	
3D Model	Packaging Specification PK-70873-0818 (PDF)
Drawing (PDF)	Test Summary TS-73670-990-001 (PDF)
Product Specification PS-73670-9999 (PDF)	RoHS Certificate of Compliance (PDF)

Agency Certification

CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73642
Application	Backplane
Comments	Standard Press-Fit, Standard Press-Fit
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800754345071

Physical

Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Net Weight	3.371/g
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.60mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.051µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

EU ELV

Not Relevant

EU RoHS

Compliant

China RoHS

REACH SVHC

Not Contained Per -
ED/71/2019 (16 July
2019)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS	Green Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series

[73642](#) Series

Mates With

[73632](#) HDM+ Board-to-Board Daughtercard
Receptacle. [73780](#) HDM Board-to-Board
Daughtercard Receptacle

Application Tooling | FAQ

*Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.*

Global

Description	Product #
Extraction Tool	621001000
Backplane Insertion	621001400
Signal Contact Tool	
Removal Tool	621007600
Backplane Signal	622008502
Insertion Module	
Press-In Tool for 2.00mm Pitch HDM*	

		Board-to-Board Backplane Header
Electrical		
Current - Maximum per Contact	1.0A	
Data Rate	1.0 Gbps	
Real Signals (per 25mm)	75	
Shielded	No	
Voltage - Maximum	250V AC	
Solder Process Data		
Lead-freeProcess Capability	N/A	
Material Info		
Reference - Drawing Numbers		
Packaging Specification	PK-70873-0818	
Product Specification	PS-73670-9999	
Sales Drawing	SDA-73642-XXXX	
Test Summary	TS-73670-990-001	

This document was generated on 09/14/2019

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